

Product / Process Change Notification



N° 2017-107-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of Copper Wire Bond and Infineon Kulim, Malaysia as Wafer Fab and Wafer Test Location affecting TLE723xSL

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **28. February 2018**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: “**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Product / Process Change Notification



N° 2017-107-A

► **Products affected:**

Sales Name	SP N°	OPN	Package
TLE7237SL	SP000670304	TLE7237SLXUMA1	PG-SSOP-24
TLE7238SL	SP000670306	TLE7238SLXUMA1	PG-SSOP-24
TLE7239SL	SP000670308	TLE7239SLXUMA1	PG-SSOP-24

► **Detailed Change Information:**

Subject: Introduction of copper wire bond and new wafer fab and new wafer test location affecting TLE723xSL.

Reason: Copper (Cu) wire bonding is part of Infineon's continuous drive to deliver higher performance products. A copper wire enables superior electrical, thermal and reliability performance compared to Gold (Au), making it an excellent interconnect solution for automotive packaging.

Transfer of wafer production and wafer test capacity. Due to continuously raising demand for Infineon automotive products we have to implement the well-known front end (FE) location Kulim as an wafer fab and wafer test location.

Description:	<u>Old</u>	<u>New</u>
Wafer fab location	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Regensburg, Germany 	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Kulim, Malaysia
Wafer test location	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Villach, Germany 	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Kulim, Malaysia
Wire bond	<ul style="list-style-type: none"> ■ Gold 30 µm 	<ul style="list-style-type: none"> ■ Copper 30 µm
Glue	<ul style="list-style-type: none"> ■ EN4900 	<ul style="list-style-type: none"> ■ A3230
Datasheet	<ul style="list-style-type: none"> ■ Rev. 1.1 	<ul style="list-style-type: none"> ■ Rev1.2
SP N°	<ul style="list-style-type: none"> ■ SP000670304 ■ SP000670306 ■ SP000670308 	<ul style="list-style-type: none"> ■ SP001973432 ■ SP001973430 ■ SP001973428
Marking	<ul style="list-style-type: none"> ■ Date Code RU lot # 	<ul style="list-style-type: none"> ■ CU Date Code 1E lot #

► **Product Identification:** Traceability assured via Lot number and new SP ordering numbers.

► **Impact of Change:** Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No impact on fit and form.

Product / Process Change Notification



N° 2017-107-A

► **Attachments:**

4_cip17107 Data Sheet Update Rev 1.2

► **Time Schedule:**

■ Final qualification report:

available

■ First samples available:

April 2018

■ Intended start of delivery:

01-July-2018 or earlier according to customer release

If you have any questions, please do not hesitate to contact your local Sales office.